SDAS002B - MARCH 1984 - REVISED DECEMBER 1994

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

#### description

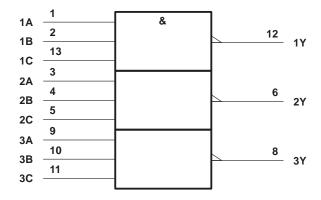
These devices contain three independent 3-input positive-NAND gates. They perform the Boolean functions  $Y = \overline{A} \bullet \overline{B} \bullet \overline{C}$  or  $Y = \overline{A} + \overline{B} + \overline{C}$  in positive logic.

The SN54ALS10A and SN54AS10 are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS10A and SN74AS10 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

	INPUTS		OUTPUT
Α	В	С	Y
Н	Н	Н	L
L	X	Χ	н
Х	L	Χ	н
Х	X	L	Н

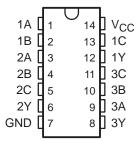
# logic symbol†



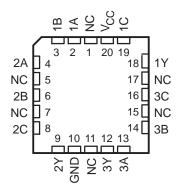
<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

#### SN54ALS10A, SN54AS10 . . . J PACKAGE SN74ALS10A, SN74AS10 . . . D OR N PACKAGE (TOP VIEW)

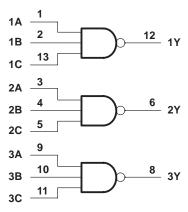


# SN54ALS10A, SN54AS10 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### logic diagram (positive logic)



## SN54ALS10A, SN54AS10, SN74ALS10A, SN74AS10 TRIPLE 3-INPUT POSITIVE-NAND GATES

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

## recommended operating conditions

		SN	SN54ALS10A		SN	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
.,	Low-level input voltage			0.8‡			0.8	V
VIL				0.7§				V
IOH	High-level output current			-0.4			-0.4	mA
l <sub>OL</sub>	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0	•	70	°C

<sup>‡</sup> Applies over temperature range -55°C to 70°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN	54ALS1	0A	SN	74ALS1	0A	UNIT
PARAMETER	1251 00	CNOTTIONS	MIN	TYP¶	MAX	MIN	TYP¶	MAX	UNII
VIK	$V_{CC} = 4.5 \text{ V},$	$I_I = -18 \text{ mA}$			-1.5			-1.5	V
VOH	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2	2		V <sub>CC</sub> -2	2		V
Vo	V <sub>CC</sub> = 4.5 V	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
VOL	VCC = 4.3 V	$I_{OL} = 8 \text{ mA}$					0.35	0.5	V
l <sub>l</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 7 V			0.1			0.1	mA
lн	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 2.7 V			20			20	μΑ
Ι <sub>ΙL</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0.4 V			-0.1			-0.1	mA
IO#	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
Іссн	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0		0.32	0.6		0.32	0.6	mA
l <sub>CCL</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 4.5 V		1.2	2.2		1.2	2.2	mA

<sup>¶</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>§</sup> Applies over temperature range 70°C to 125°C

<sup>#</sup>The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

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#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub> C <sub>L</sub> R <sub>L</sub> T <sub>A</sub>	UNIT			
			SN54A	LS10A	SN74AI	LS10A	
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A, B, or C	V	2	12	2	11	ns
<sup>t</sup> PHL	A, D, 01 C	1	2	12	2	10	115

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	 7 V
Input voltage, V <sub>I</sub>	 7 V
Operating free-air temperature range, T <sub>A</sub> : SN54AS10	
SN74AS10	 0°C to 70°C
Storage temperature range	 -65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		SN54AS10			S	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-2			-2	mA
loL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		SI	SN54AS10		S	N74AS1	0	UNIT
PARAMETER	lesi co	NUTTIONS	MIN	TYP§	MAX	MIN	TYP§	MAX	UNII
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{ } = -18 \text{ mA}$			-1.2			-1.2	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2	!		V <sub>CC</sub> -2	2		V
V <sub>OL</sub>	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.35	0.5		0.35	0.5	V
lį	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1			0.1	mA
lін	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μΑ
I <sub>I</sub> L	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V			-0.5			-0.5	mA
ΙΟ <sup>¶</sup>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	-30		-112	mA
ICCH	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0		1.5	2.4		1.5	2.4	mA
ICCL	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 4.5 V		8.1	13		8.1	13	mA

<sup>§</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.



The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, Ios.

# SN54ALS10A, SN54AS10, SN74ALS10A, SN74AS10 TRIPLE 3-INPUT POSITIVE-NAND GATES

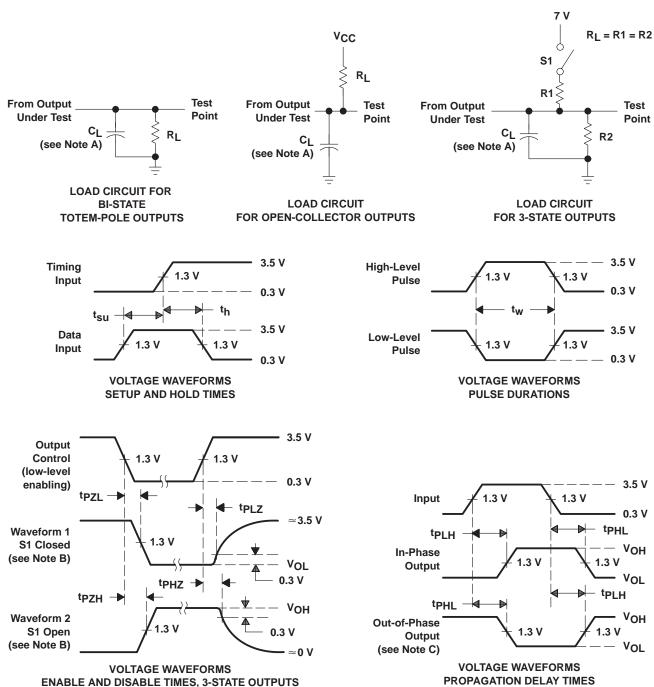
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### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub> C <sub>L</sub> R <sub>L</sub> T <sub>A</sub>	UNIT			
			MIN	MAX	SN74A MIN	MAX	
<sup>t</sup> PLH	A, B, or C	V	1	5	1	4.5	ns
<sup>t</sup> PHL	A, B, OI C	ı	1	5	1	4.5	115

 $<sup>^\</sup>dagger$  For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms









#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-86865012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
5962-8686501CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
5962-8686501DA	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type
JM38510/37002B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
JM38510/37002BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
SN54ALS10AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
SN54AS10J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
SN74ALS10AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS10ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS10ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS10ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS10AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS10ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS10ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS10ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS10D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS10DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS10DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS10DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS10N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS10N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74AS10NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS10NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS10NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ALS10AFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54ALS10AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type
SNJ54ALS10AW	ACTIVE	CFP	W	14	1	TBD	Call TI	N / A for Pkg Type
SNJ54AS10FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54AS10J	ACTIVE	CDIP	J	14	1	TBD	Call TI	N / A for Pkg Type

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.



#### PACKAGE OPTION ADDENDUM

12-Jan-2006

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F14)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G14)

# PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



#### **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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